

WinhiSemi

WLPB2P5R286PA

Datasheet

WinhiSemi

General Description

WLPB2P5R286PA MOSFET is based on VMD Semiconductor’s unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The low V_{th} series is specially optimized for synchronous rectification systems with low driving voltage.

Symbol

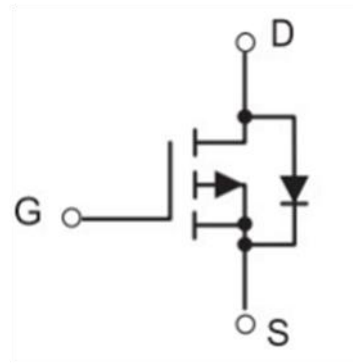


Figure 1 Symbol of WLPB2P5R286PA

Features

- $R_{DS(ON_TYP)} = 22.9m\Omega @ V_{GS} = -4.5V$
- Extremely low switching loss
- Stable performance
- Fast switching and soft recovery

Package Type



Figure 2 Package Type of WLPB2P5R286PA

Application

- Load Switch
- DC-DC converter
- Switched mode power supply
- Switching voltage regulator

Ordering Information

Product Name	Package
WLPB2P5R286PA	PDFN5*6

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-25	V
Gate-Source Voltage ^{Note 1}	V_{GSS}	±8	V
Continuous Drain Current ^{Note 2} $T_C=25^{\circ}C$	I_D	-24	A
Pulsed Drain Current ^{Note 3} , $T_C=25^{\circ}C$	I_{DM}	-72	A
Max Power Dissipation ^{Note 4} $T_C=25^{\circ}C$	P_D	24	W
Avalanche Current, Single Pulse	I_{AS}	-50	A
Avalanche Energy, Single Pulse ^{Note 5}	E_{AS}	128	mJ
Continuous Diode Forward Current ^{Note 2} $T_C=25^{\circ}C$	I_S	-24	A
Diode Pulse Current ^{Note 3} $T_C=25^{\circ}C$	$I_{S,PULSE}$	-72	A
Operation and storage temperature	T_J, T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		5.3		°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$		50		

Notes:

- 1) It is recommended that the value be less than 8V in practice.
- 2) Calculated continuous current based on maximum allowable junction temperature.
- 3) Repetitive rating;pulse width limited by max.junction temperature.
- 4) P_D is based on max.junction temperature,using junction-case thermal resistance.
- 5) $V_{DS}=-24V, V_{GS}=-4.5 V, L=0.1 mH,$ starting $T_J=25^{\circ}C$.

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-25			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20V, V_{GS}=0V$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 8V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4		-1.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-15A$		22.9	28.6	$m\Omega$
		$V_{GS}=-6V, I_D=-15A$		21.8	27.2	$m\Omega$
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$		0.5		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=-10V$		1821		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		804		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		534		pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=-15V$		10.6		ns
Rise Time	t_r	$I_D=-15A$		35		
Turn-off Delay Time	$t_{d(off)}$	$R_G=4.7\Omega$		45.3		
Fall Time	t_f	$V_{GS}=-4.5V$		57.3		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DS}=-15V$		3.5		nC
Gate to Drain Charge	Q_{gd}	$I_D=-15A$		13		
Gate Charge Total	Q_g	$V_{GS}=-4.5V$		31.8		
Gate Plateau Voltage	$V_{plateau}$			-1.5		V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=-15A$		-1.0		V
Reverse Recovery Time	t_{rr}	$V_R=15V$		31		ns
Reverse Recovery Charge	Q_{rr}	$I_F=1A$		25		nC
Peak Reverse Recovery Current	I_{rrm}	$dI_F/dt=100A/\mu s$		1.5		A

Typical Performance Characteristics

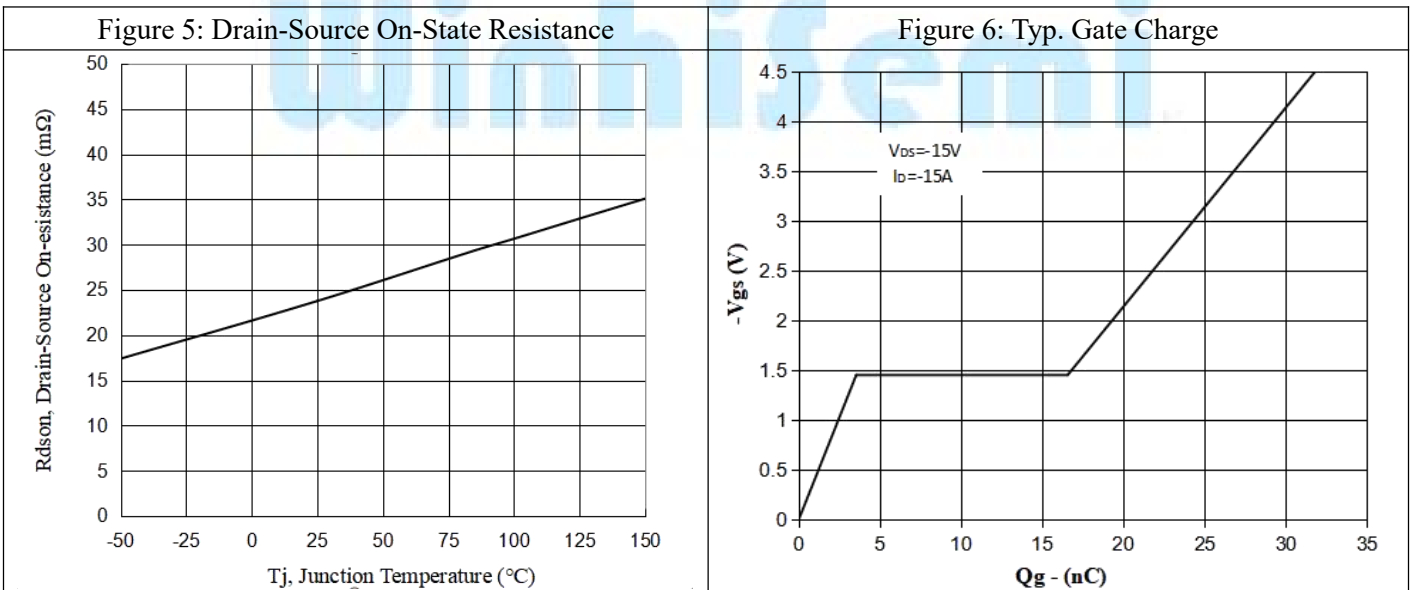
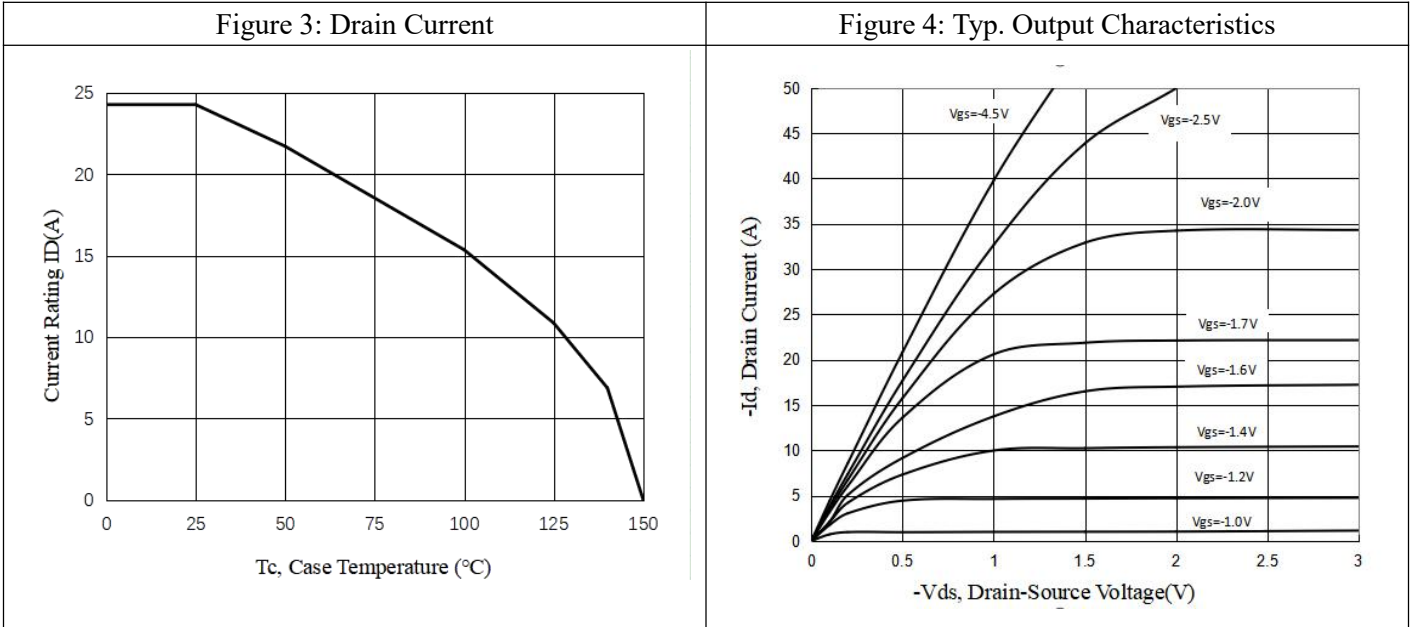


Figure 7: Typ. Capacitance

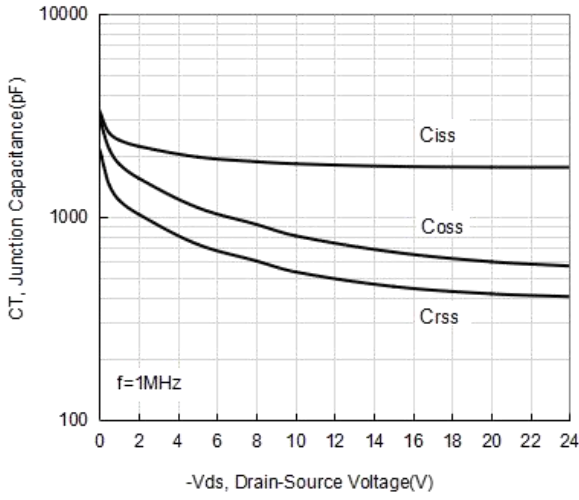


Figure 8: Forward Characteristics of Body Diode

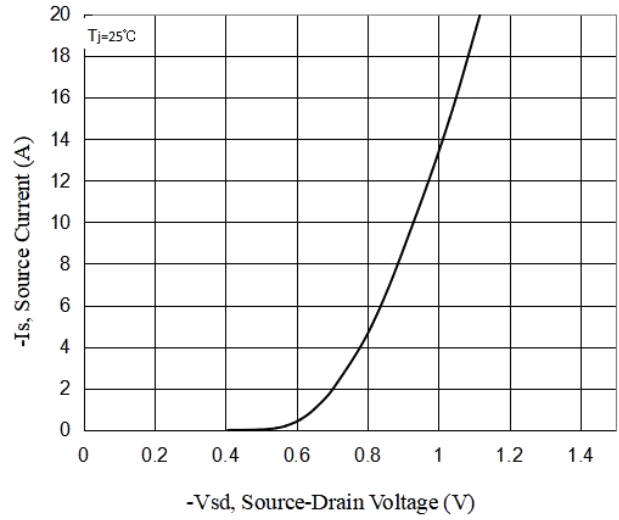


Figure 9: Typ. transfer characteristics

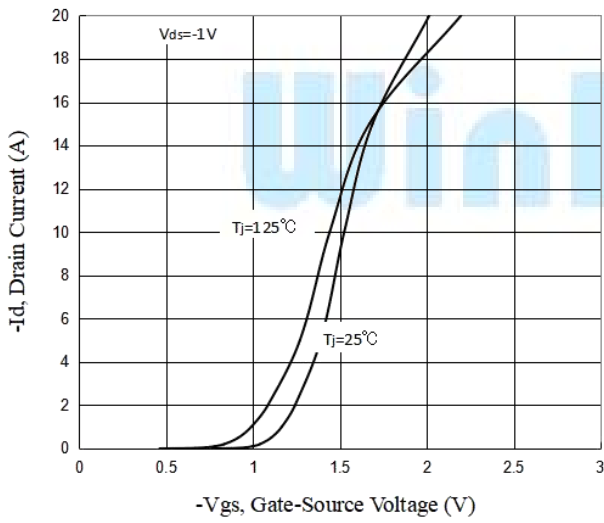
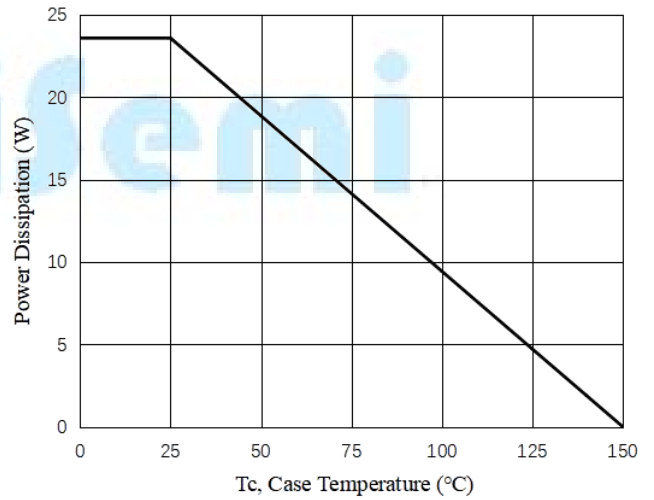
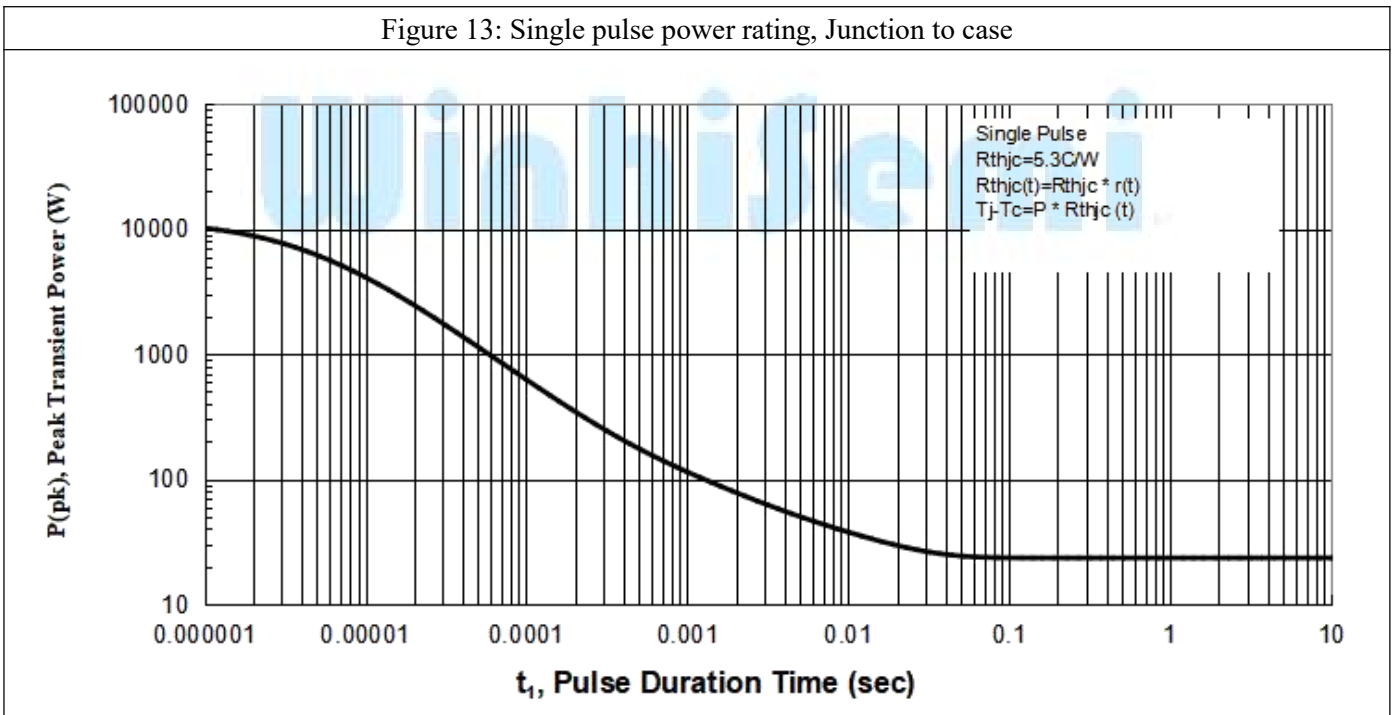
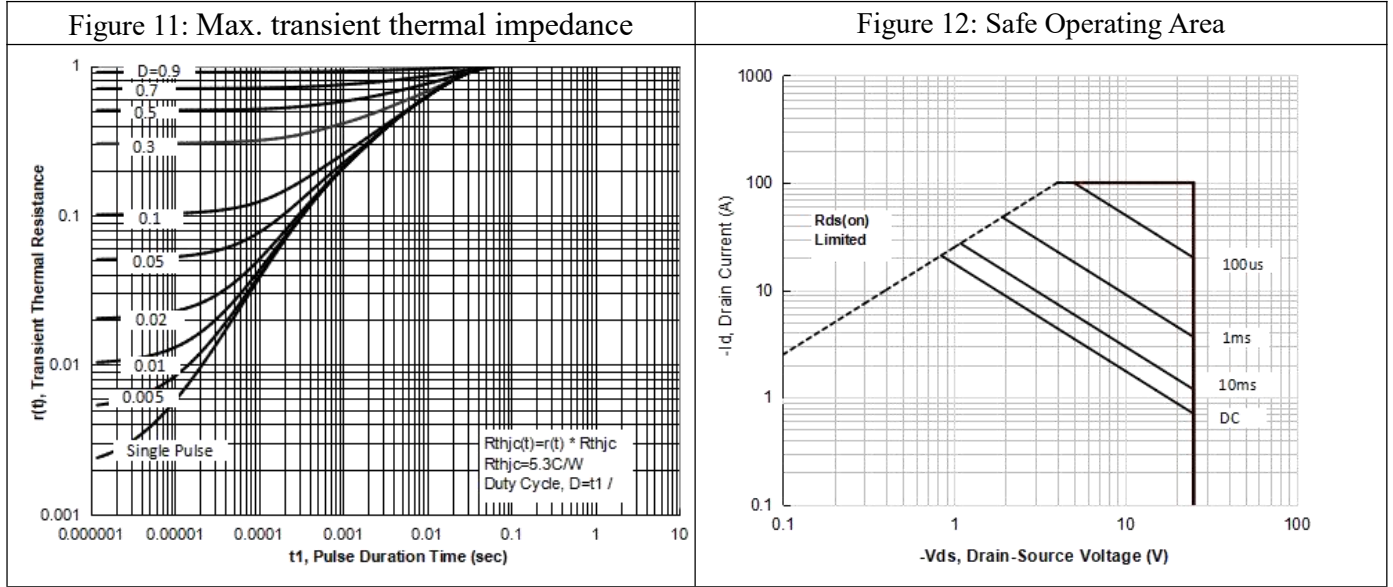
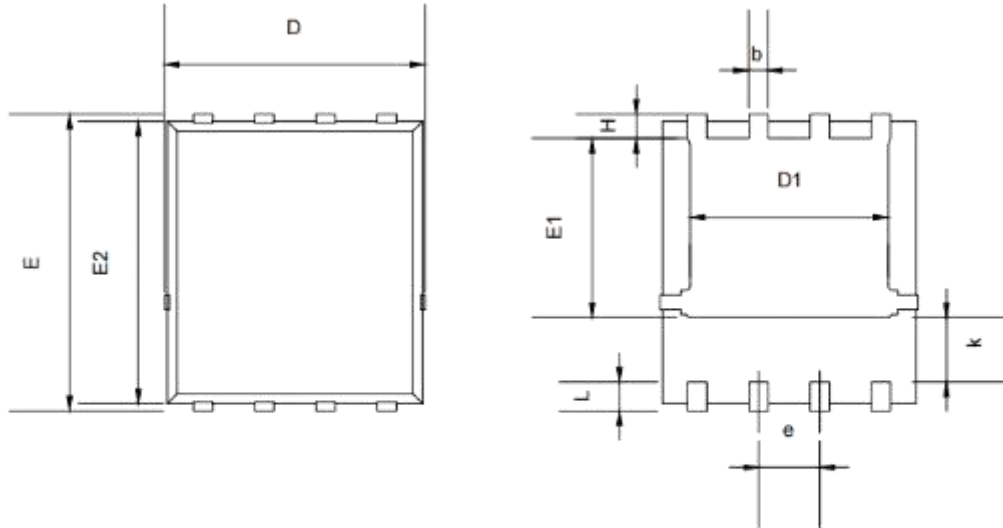


Figure 10: Max Power Dissipation





Mechanical Dimensions (PDFN5*6 Unit: mm)



Symbol	Dimensions(mm)	
	Min.	Max.
A	0.90	1.20
C	0.15	0.35
D	4.80	5.40
D1	3.61	4.31
E	5.90	6.35
E1	3.30	3.92
E2	5.50	6.06
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
H	0.38	0.71
θ	0°	12°

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